

Notice of References Cited	Application/Control No. 10/721,966	Applicant(s)/Patent Under Reexamination BUDELL ET AL.	
	Examiner Toan M. Le	Art Unit 2863	Page 1 of 1

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	X	Chandrasekhar et al., Modeling and Characterization of the Polymer Stud Grid Array (PSGA) Package: Electrical, Thermal and Thermo-Mechanical Qualification, 2001 Electronic Components and Technology Conference

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.